

Patent Abstracts of Japan

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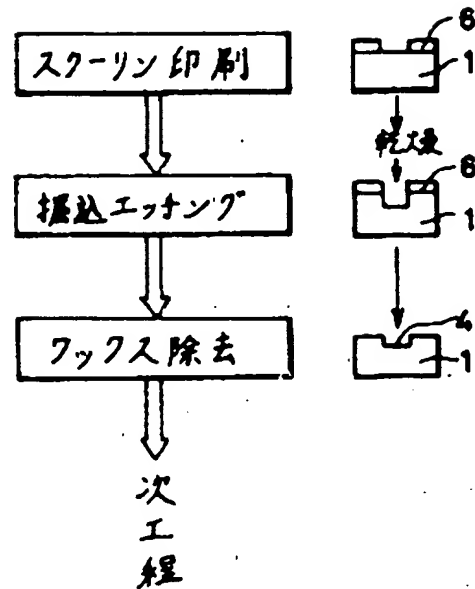
APPLICATION DATE : 16-04-79
APPLICATION NUMBER : 54047107

APPLICANT : MEIDENSHA ELECTRIC MFG CO LTD;

INVENTOR : SUZUKI TAKAHIRO;

INT.CL. : H01L 21/30

TITLE : METHOD OF FORMING PATTERN ON SEMICONDUCTOR ELEMENT



ABSTRACT : PURPOSE: To largely omit the number of processing steps in a method of forming a pattern on a semiconductor element and to form an accurate and preferable pattern thereon by screen printing a mask material made of wax and solvent thereon and then deeply etching the masked wafer.

CONSTITUTION: A wax material 6 made of wax such as apiezon series wax and solvent such as butylcarbylacetate series solvent is screen printed as a mask agent on a semiconductor element wafer 1. Then, the wafer 1 is dried and then deeply etched to form a pattern 4 thereon. The wax material 6 is then removed therefrom. It is noted that after an oxide film is formed on the wafer 1, the wax material 6 is screen printed thereon as required.

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